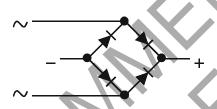
### 0.8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

### **Features and Benefits**

- Glass Passivated Die Construction
- Low Forward Voltage Drop
- Surge Overload Rating to 30A Peak
- Ideally Suited for Automated Assembly
- Miniature Package Saves Space on PC Boards
- UL Listed Under Recognized Component Index, File Number E94661
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

### **Mechanical Data**

- Case: MiniDIP
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Tin. Plated Leads, Solderable per MIL-STD-202, Method 208 @3
- Polarity: As Marked on Case
- Marking: Product Type Marking Code, Date Code, & Polarity
- Weight: 0.125 grams (Approximate)



Equivalent Circuit

## Ordering Information (Note 3)

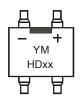
Part Number*	~	Packaging	Shipping
HDxx-T		MiniDIP	3k/Tape & Reel, 13-inch

<sup>\*</sup>xx = Device type, e.g. HD02-T or HD04-T, etc.

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied. 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and
- 3. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**



HDxx = Product Type Marking Code (ex: HD04) YM = Date Code Marking Y = Last Digit of the Year M = See Month/Code Table Below

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	HD01	HD02	HD04	HD06	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RMM</sub> V <sub>RWM</sub> V <sub>DC</sub>	100	200	400	600	>
RMS Reverse Voltage	V <sub>RMS</sub>	70	140	280	420	V
Average Forward Rectified Current (Note 4) @T <sub>A</sub> = +40°C	lo		0	.8		Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>		3	30		Α

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 4)	$R_{\theta JA}$	75	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

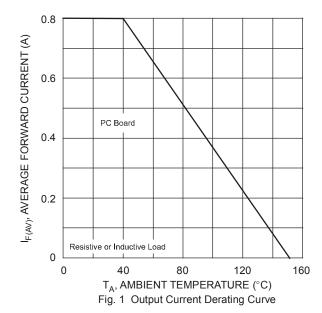
## Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

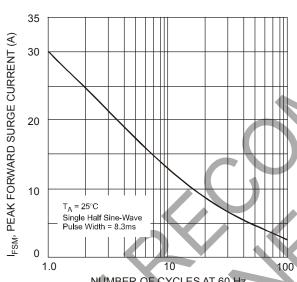
Characteristic	Symbol	Value	Unit
Instantaneous Voltage Drop @ 0.4A (Per Element)	V <sub>F</sub>	1.0	V
Peak Reverse Current at Rated @T <sub>A</sub> = +25°C	4	5.0	μA
DC Blocking Voltage (Per Element) @T <sub>A</sub> = +125°C	IR	500	μΛ
Typical Total Capacitance (Per Element) (Note 5)	C <sub>T</sub>	10	pF

Notes:

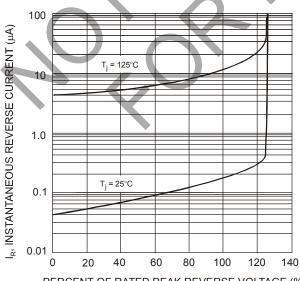
- 4. Mounted on PC Board.
- 5. Measured at 1.0MHz and applied reverse voltage of 4.0V.



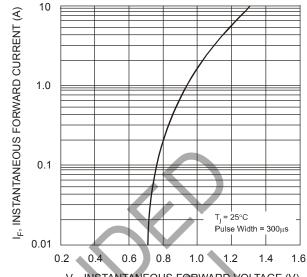




NUMBER OF CYCLES AT 60 Hz Fig. 3 Maximum Peak Forward Surge Current (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%) Fig. 5 Typical Reverse Characteristics (per element)



V<sub>F</sub>, INSTANTANEOUS FORWARD VOLTAGE (V) Fig. 2 Typical Forward Characteristics (per element)

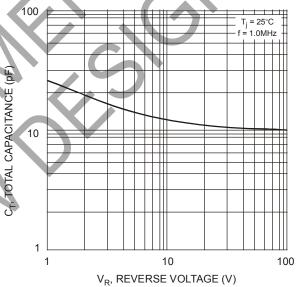


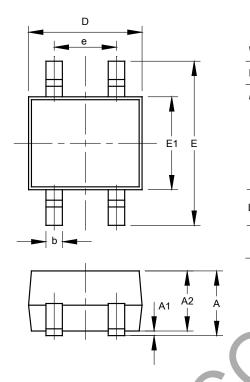
Fig. 4 Typical Total Capacitance (per element)



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **MiniDIP**



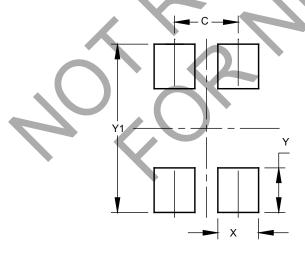
\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	A2a		
<b>V</b>	1		
L1	,		

MiniDIP				
Dim	Min	Max		
Α		3.00		
A1		0.20		
A2	2.30	2.70		
A2a	1.20	1.60		
b	0.50	0.80		
С	0.15	0.35		
D	4.50	4.90		
Е		7.00		
E1	3.60	4.00		
е	2.30	2.70		
L	0.70	1.10		
L1	1.10	2.12		
All Dim	ensions	in mm		

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

## MiniDIP



Dimensions	Value (in
Dillielisiolis	mm)
С	2.50
Χ	1.65
Υ	1.80
Y1	6.80



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  - 2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.
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